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6/3/04 MT

L Number	Hits	Search Text	DB	Time stamp
1	2	6662440.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:43
2	10	("3941636"   "4126727"   "4648179"   "5068714"   "5415555"   "5669970"   "5740730"   "5866951"   "6118080"   "6162856").PN.	USPAT	2004/06/03 13:05
3	10	("3941636"   "4126727"   "4648179"   "5068714"   "5415555"   "5669970"   "5740730"   "5866951"   "6118080"   "6162856").PN.	USPAT	2004/06/03 13:10
4	68	stencil and inner and outer near member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:16
5	7	("2997777"   "3923936"   "4526098"   "4911069"   "5181549"   "5215724"   "5662040").PN.	USPAT	2004/06/03 13:14
6	6	("3877364"   "4537658"   "4541895"   "4911069"   "5245932"   "5588359").PN.	USPAT	2004/06/03 13:15
7	0	stencil and inner and annular near opening and outer and inner near member and (101/128.21, 101/116 , 101/128.4 , 118/504 ) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:18
8	0	stencil and annular near opening and outer and inner near member and (101/128.21, 101/116 , 101/128.4 , 118/504 ).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19
9	2	stencil and annular near opening and outer and inner and (101/128.21, 101/116 , 101/128.4 , 118/504 ).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19
10	2	stencil and annular near opening and (101/128.21, 101/116 , 101/128.4 , 118/504 ) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19

11	4	stencil and annular near opening and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:38
12	10	("3941636"   "4126727"   "4648179"   "5068714"   "5415555"   "5669970"   "5740730"   "5866951"   "6118080"   "6162856").PN.	USPAT	2004/06/03 13:36
13	1	stencil and annular near opening and (101/127, 101/115 , 118/213 , 118/406 , 228/175 , 228/180.22, 427/282 , 427/96).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:42
14	2	("Re34615"   "5522929").PN.	USPAT	2004/06/03 13:41
15	5	stencil and annular near opening and (29/840, 174/253 , 174/255 , 257/737 , 257/738 , 257/E21.514, 29/832 , 29/842 , 29/846).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48
16	227	Jiang near Tongbi .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:43
17	52	Jiang near Tongbi .inv. and stencil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48
18	14	("3668028"   "4088073"   "4269874"   "4398462"   "4862245"   "5240816"   "5447757"   "5460316"   "5478699"   "5579583"   "5887520"   "6016746"   "6060117"   "6146489").PN.	USPAT	2004/06/03 13:46
19	2	stencil and annular near opening and (438/118, 101/127 , 101/128.21 , 101/128.4 , 438/584).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48

	<b>Title</b>	<b>Current OR</b>
<b>1</b>	<b>Reflective composition of particles with resinous binder and process for preparing same</b>	<b>524/441</b>
<b>2</b>	<b>Z-axis electrical contact for microelectronic devices</b>	<b>174/253</b>
<b>3</b>	<b>Hybrid circuit with an electrically conductive adhesive</b>	<b>257/783</b>
<b>4</b>	<b>Apparatus for depositing solder and adhesive materials onto a printed circuit board</b>	<b>101/127</b>
<b>5</b>	<b>Stencil apparatus for applying solder paste</b>	<b>118/213</b>
<b>6</b>	<b>Electrical interconnection apparatus utilizing raised connecting means</b>	<b>439/74</b>

	<b>Title</b>	<b>Current OR</b>
<b>7</b>	<b>Method of electrically and mechanically connecting a semiconductor to a substrate using an electrically conductive tacky adhesive and the device so made</b>	<b>257/703</b>
<b>8</b>	<b>Process of making interconnection structure for semiconductor device</b>	<b>29/832</b>
<b>9</b>	<b>Resinous polymer sheet materials having selective, decorative effects</b>	<b>428/172</b>

	<b>Title</b>	<b>Current OR</b>
<b>10</b>	<b>Process for forming decorative surface coverings</b>	<b>156/154</b>